DOCUMENT CHANGE REQUEST

DCR number 980	Changes required for: General	Originator: Steve Thacker	
Date: 2016/02/29	Date sent: 2016/02/25	Organisation: ESCC Executive Secretariat	
Status: IMPLEMENTED			

Title:	Evaluation Test Programme for Monolithic Integrated Circuits		
Number:	2269000	Issue:	4

Other documents affected:

Page:

This is a major revision; most pages have been affected. See attached 2269000 draft 5C (2016-02-25) with track changes.docx for details

Paragraph:

This is a major revision; most paragraphs have been affected. See attached 2269000 draft 5C (2016-02-25) with track changes.docx for details

Original wording:

As per ESCC 2269000 issue 4

Proposed wording:

Specification is amended to add requirements applicable to Monolithic Flip-chip Integrated Circuit components in both Hermetic and Non-Hermetic Packages as well as Multichip, Wire-bonded Integrated Circuit components in Hermetic Packages (in addition to the currently specified Monolithic Wire-bonded Integrated Circuit components in Hermetic Packages).

Full details of the changes to ESCC 2269000 issue 4 are as indicated by the Track Changes shown in the attached MSWORD 2010 draft specification ESCC 2269000 draft 5C.

Note: a finalised version of 2269000 Draft 5C is also attached for information purposes.

A summary of the changes is as follows:

1) General editorial changes for clarification purposes including renumbering of paragraphs and clarification of the current requirements that still apply to Wire-bonded IC components plus several minor amendments including adding reference to multichip microcircuits.

2) Addition of requirements for Flip-Chip IC components. The following paragraphs are affected (see attached for details): Paras: Title, 2, 2.1, 2.2, 3(new), 4.1(new), 4.2(new), 4.1, 5.7, 5.8, 5.10, 7.3.1, 7.3.4.1, 8.3.4.2(new), 7.3.4.3, 7.3.4.5, 7.3.4.6, .8.3.4.9(new), 7.3.5.2, 8.3.5.2.2(new), 7.3.5.3, 8.3.5.3.2(new), 8.3.5.6(new), 8.3.7/8.3.7.1(new), 8.4.5(new), 8.1, 8.12, 8.13, 9.15(new), 9.16.4(new), Chart I (Charts IA, IB, IC(new))

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3) Para 2.2 & 5.10: PSS-01-702 is replaced by reference to ECSS-Q-ST-70-02 for outgassing.

4) Para 7.3.4.4 SEM Inspection: add requirements for deep sub-micron devices

5) Para 7.3.4.7 Microsectioning: add requirements for CGA packages

Justification:

Item 1: minor changes for consistency and clarification purposes.

Item 1, 2: to add requirements for Flip-chip IC components in line with the ESA Working Group conclusions.

Item 3: replacement of obsolete reference specs.

Item 4, 5: additional changes to ESCC 2269000 in line with the ESA Working Group conclusions.

Attachments:

2269000_draft_5c_(2016_02_25)_with_track_changes.docx, 2269000_draft_5c_(2016_02_25)_finalised.docx

Modifications:

N/A

Approval signature:



Date signed:

2016-02-29